



Protects one bi-directional I/O line
 Low clamping voltage
 Low operating voltage: 36V
 RoHS compliant



Cell phone handsets and accessories
 Personal digital assistants (PDA's)
 Notebooks, desktops, and servers
 Portable instrumentation
 Pagers
 Microprocessor based equipment

IEC61000-4-2 (ESD) ±30kV (air), ±30kV (contact)
 IEC61000-4-4 (EFT) 40A (5/50ns)
 IEC61000-4-5 (Lightning) 4A (8/20µs)

DFN1006-2L package
 Molding compound flammability rating : UL 94V-0
 Quantity per reel : 10,000pcs
 Lead finish : lead free
 Marking code CF

(T_A=25°C, RH=45%-75%, unless otherwise noted)

| Parameter | Symbol | Value | Unit |
|---|------------------|---------------|------|
| Peak pulse power dissipation at 8/20µs waveform | P _{PP} | 400 | W |
| ESD per IEC 61000-4-2 (Air) | V _{ESD} | +/-30 | kV |
| ESD per IEC 61000-4-2 (Contact) | | +/-30 | |
| Lead soldering temperature | T _L | 260 (10 sec.) | |
| Operating junction temperature range | T _J | -55 to +125 | |
| Storage temperature range | T _{STG} | -55 to +150 | |

($T_A=25$)

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|---------------------------|-----------|----------------------------|-----|-----|-----|---------|
| Reverse working voltage | V_{RWM} | | | | 36 | V |
| Reverse breakdown voltage | V_{BR} | $I_T=1mA$ | 40 | | | V |
| Reverse leakage current | I_R | $V_{RWM}=36V$ | | | 1 | μA |
| Peak pulse current | I_{PP} | $t_P=8/20\mu s$ | | | 4 | A |
| Clamping voltage | V_C | $I_{PP}=1A, t_P=8/20\mu s$ | | 50 | 55 | V |
| | | $I_{PP}=4A, t_P=8/20\mu s$ | | 64 | 70 | |
| Junction capacitance | C_J | $V_{RWM}=0V, f=1MHz$ | | 11 | | pF |

($T_A=25$, unless otherwise noted)

FIG.1: V- I curve characteristics (Bi-directional)

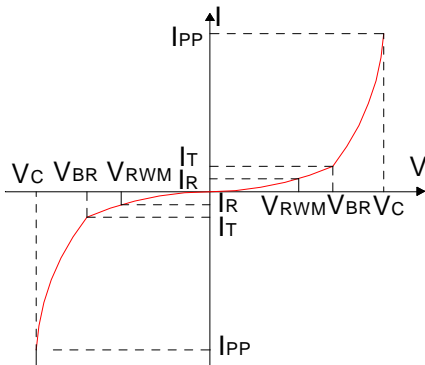


FIG.2: Pulse waveform (8/20 μs)

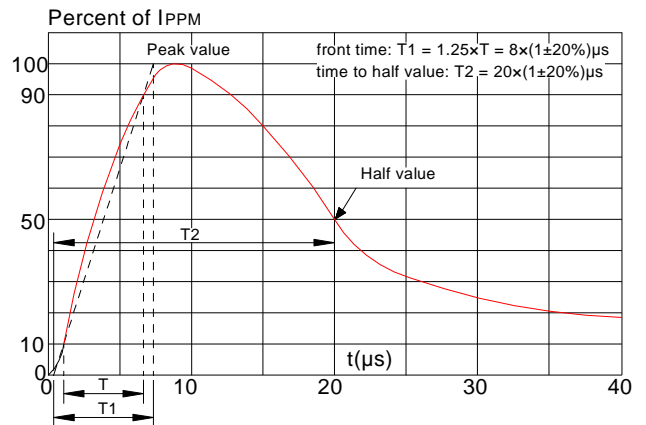


FIG.3: Pulse derating curve

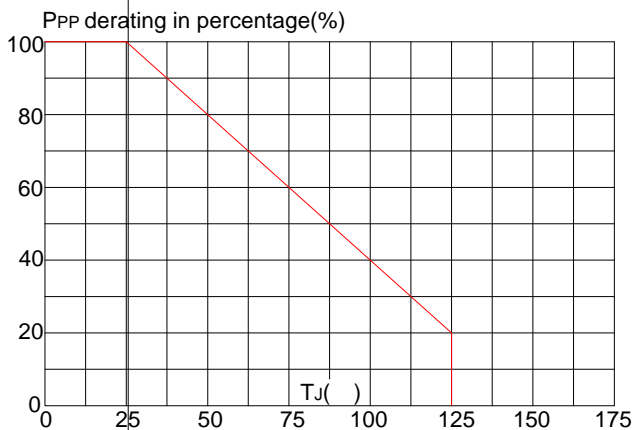
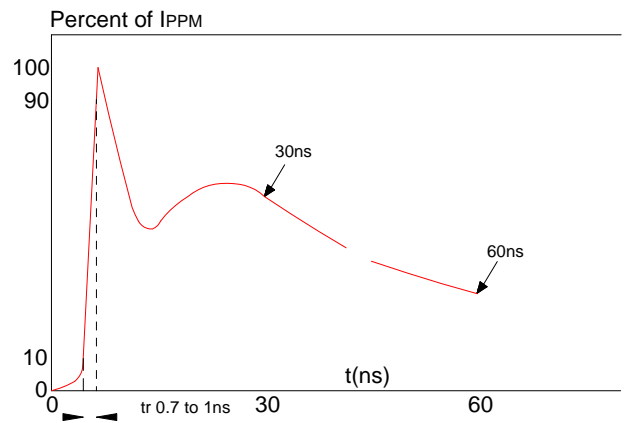
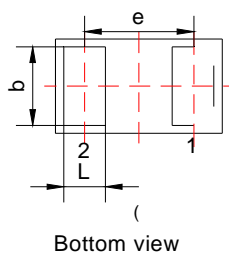
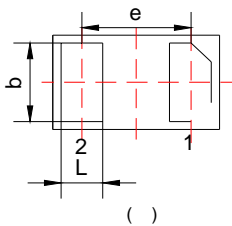
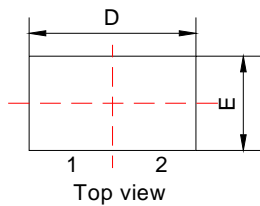


FIG.4: ESD clamping (30kV contact)

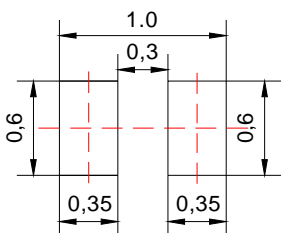


| | | |
|---|-----------------------------------|---|
| Reflow Condition | | Pb-Free assembly (see figure at right) |
| Pre Heat | -Temperature Min ($T_{s(min)}$) | +150 |
| | -Temperature Max($T_{s(max)}$) | +200 |
| | -Time (Min to Max) (ts) | 60-180 secs. |
| Average ramp up rate (Liquidus Temp (T_L)to peak) | | 3 /sec. Max |
| $T_{s(max)}$ to T_L - Ramp-up Rate | | 3 /sec. Max |

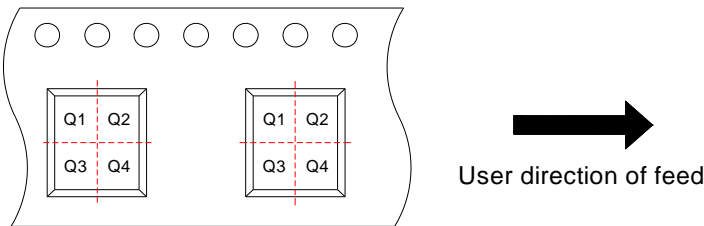
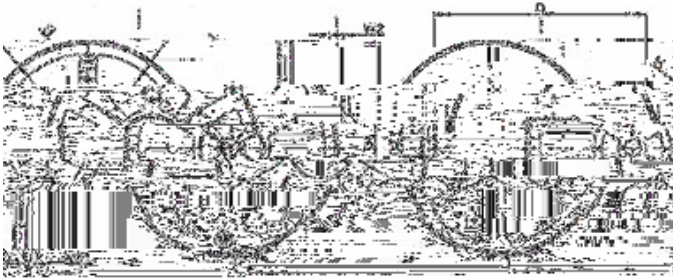
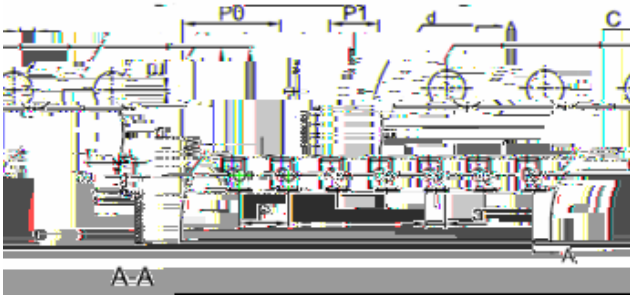
Reflow -Temperature(T_L)



Side view



Recommended soldering footprint(mm)



Pin 1 quadrant:Q1&Q2

Packaging Description:

DFN1006-2L parts are shipped in tape. The carrier tape is made from a dissipative(carbon filled) polycarbonate resin. The cover tape is a multilayer film(heat activated adhesive in nature)primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 10,000units per 7" or 17.8cm diameter reel. The reels are clear in color and made of polystyrene plastic(anti-static coated).

| Symbol | Millimeters | Inches |
|--------|-------------|--------|
| | Typ. | Typ. |
| a | 0.66 | 0.026 |
| B | 1.15 | 0.045 |
| C | 0.66 | 0.026 |
| d | 1.50 | 0.059 |
| E | 1.75 | 0.069 |
| F | 3.50 | 0.138 |
| P0 | 4.00 | 0.157 |
| P | 2.00 | 0.079 |
| P1 | 2.00 | 0.079 |
| W | 8.00 | 0.315 |
| D | 178 | 7.008 |
| D1 | 54.40 | 2.142 |
| D2 | 13.00 | 0.512 |
| G | R78.00 | R3.071 |
| H | R25.60 | R1.008 |
| I | R6.50 | R0.256 |
| W1 | 9.50 | 0.374 |
| W2 | 12.30 | 0.484 |

| PART No. | PACKAGE TYPE | QUANTITY(PCS) REEL | DESCRIPTION |
|----------|--------------|-----------------------|------------------|
| JEB36DFP | DFN1006-2L | 10,000 | 7 inch reel pack |

for ESD Protection

JieJie Microelectronics Co., Ltd.